MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

TSSOP56 14x6.1
CASE 948BR
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DATE 30 SEP 2016

NOTES:
A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION EE, REF NOTE 6, DATE 10/97.
B. DIMENSIONS ARE IN MILLIMETERS.
C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

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